

HSS104

Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0571-0300

(Previous: ADE-208-178B)

Rev.3.00 Mar 25, 2005

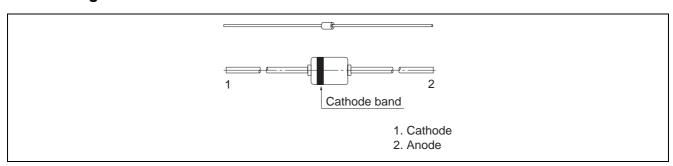
Features

- Short reverse recovery time and forward recovery time.
- Suitable for 5 mm pitch high speed automatically insertion.
- Small glass package (MHD) enables easy mounting and high reliability.

Ordering Information

Type No.	Cathode band	Package Name	Package Code (Previous Code)
HSS104	Blue	MHD	GRZZ0002ZC-A
			(MHD)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	40	V
Reverse voltage	V _R	35	V
Average rectified current	I ₀	110	mA
Peak forward current	I _{FM}	300	mA
Non-Repetitive peak forward surge current	I _{FSM} *	400	mA
Power dissipation	Pd	300	mW
Junction temperature	Tj	175	°C
Storage temperature	Tstg	-65 to +175	°C

Note: Within 1s forward surge current.

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V_{F}	1		1.2	>	I _F = 100 mA
Reverse current	I _R	_	_	0.5	μΑ	V _R = 35 V
Capacitance	С	_	_	3.0	pF	V _R = 0.5 V, f = 1 MHz
Reverse recovery time	t _{rr}			3.0	ns	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 50 \Omega$

Main Characteristic

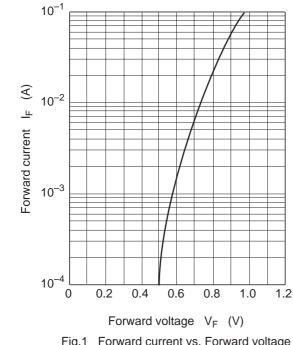


Fig.1 Forward current vs. Forward voltage

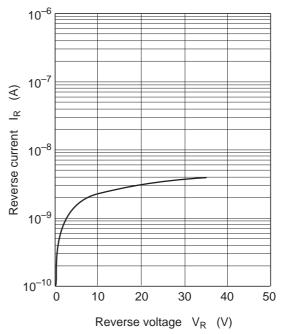
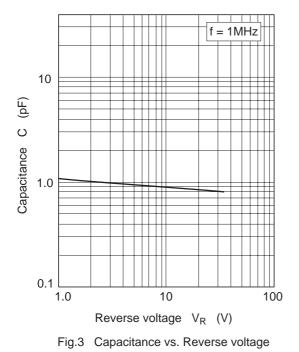
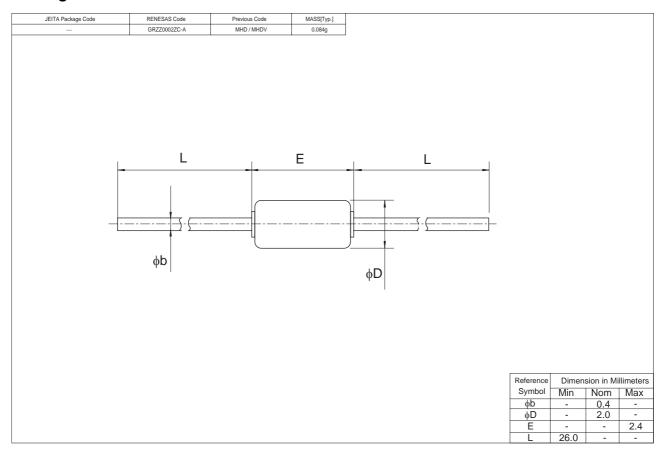


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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